



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20251016000.1

**Qualify TIEM and CDAT as an additional Assembly site for select devices
Change Notification / Sample Request**

Date: October 16, 2025
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20251016000.1
Attachment: 1

Products Affected:


The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LM339PWR	LM339PWR
SN74LVC07APWR	NULL
ULN2003AIPWR	ULN2003AIPWR
CD74HC4051PWR	CD74HC4051PWR
SN74LV07APWRG3	NULL
LM239PWR	NULL
SN74LV8T594PWR	NULL
LM339APWR	NULL
SN74LVC08APWR	NULL
SN74LVC125APWR	NULL
SN74LV164APWR	NULL
CD4504BPWR	NULL
TS3A5018PWR	TS3A5018PWR
SN74AHC594PWR	SN74AHC594PWR
SN74LV4051APWR	NULL
SN74LVC14APWR	NULL
SN74LV4052APWR	SN74LV4052APWR
SN74AHC125PWR	NULL
SN74LVC00APWR	NULL
CD74HC4052PWR	CD74HC4052PWR
LM2901PWR	LM2901PWR
CD4093BPWR	NULL
TLV9064IPWR	NULL
SN74LV8T165PWR	NULL
ULN2003APWR	ULN2003APWR
TCA9546APWR	TCA9546APWR
TLV9054IPWR	TLV9054IPWR

Technical details of this Product Change follow on the next page(s).

PCN Number:	20251016000.1		PCN Date:	October 16, 2025
Title:	Qualify TIEM and CDAT as an additional Assembly sites for select devices			
Customer Contact:	Change Management team		Dept:	Quality Services
Proposed 1st Ship Date:	January 14, 2026		Sample requests accepted until:	December 15, 2025*
*Sample requests received after December 15, 2025 will not be supported.				
Change Type:				
<input checked="" type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Material		
<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Process		
<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Fab Site		
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Material		
<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Process		
PCN Details				
Description of Change:				
Texas Instruments is pleased to announce the qualification of TI Melaka (TIEM) and TI Chengdu (CDAT) as an additional Assembly sites for the list of devices shown below. Material differences between sites are as follows.				
	Current site		Additional Sites	
Assembly site	TFME*	MLA	TIEM/CDAT	
Mount compound	SID#A-03	4147858	4211470	
Mold compound	SID#R-31	4211471	4228573	
Lead finish	Matte Sn	NiPdAu	Matte Sn	
*Applicable for SN74LV07APWRG3				
Reason for Change:				
Continuity of supply.				
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):				
None.				
Impact on Environmental Ratings				
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.				
RoHS	REACH	Green Status	IEC 62474	
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	
Changes to product identification resulting from this PCN:				
Assembly Site Information:				
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City	
TFME	NFM	CHN	Chongchuan	
MLA	MLA	MYS	Kuala Lumpur	
CDAT	CDA	CHN	Chengdu	
TIEM	CU6	MYS	Melaka	

Sample product shipping label (not actual product label)

 **TEXAS INSTRUMENTS**
 MADE IN: Malaysia
 2DC: 20:
 MSL 2 / 260C/1 YEAR SEAL DT
 MSL 1 / 235C/UNLIM 03/29/04
 OPT:
 ITEM: 39
LBL: 5A (L)T0:1750



(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483SI2
 (P)
 (2P) REV: (V) 0033317
 (20L) CS0: SHE (21L) CCO:USA
 (22L) AS0: MLA (23L) ACO: MYS

Product Affected:

AM26C31IPWR	LM339PWR	SN74LV8T594PWR	TLV9054IPWR
CD4093BPWR	SN74AHC125PWR	SN74LVC00APWR	TLV9064IPWR
CD4504BPWR	SN74AHC594PWR	SN74LVC07APWR	TS3A5018PWR
CD74HC4051PWR	SN74LV07APWRG3	SN74LVC08APWR	ULN2003AIPWR
CD74HC4052PWR	SN74LV164APWR	SN74LVC125APWR	ULN2003APWR
LM239PWR	SN74LV4051APWR	SN74LVC14APWR	
LM2901PWR	SN74LV4052APWR	TCA9546APWR	
LM339APWR	SN74LV8T165PWR	TLV2374IPWR	

Qualification Report (TIEM)

Approve Date 23-January-2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: AM26C31IPWR	Qual Device: SN74HC14PWR	QBS Reference: LM5576QMH/NOPB
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0
HTOL	B1	Life Test	125C	1000 Hours	-	-	1/77/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	3/66/0	3/66/0	1/30/0
PD	C4	Physical Dimensions	Cpk>1.67	-	3/30/0	3/30/0	3/30/0

QBS: Qual By Similarity, also known as Generic Data

Qual Device AM26C31IPWR is qualified at MSL1 260C

Qual Device SN74HC14PWR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2311-009

Qualification Report (TIEM)

Approve Date 30-June-2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: LMP7704MT/NOPB	Qual Device: LMH0346MH/NOPB	QBS Reference: LM5576QMH/NOPB	QBS Reference: LM5118Q1MH/NOPB
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-
UHAST	A3	Autoclave/UHAST	121C/15psig Or 130C/85%RH	96 Hours	3/231/0	-	3/231/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	3/231/0	-	3/135/0	3/135/0
HTOL	B1	Life Test	125C	1000 Hours	-	-	1/77/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	3/66/0	3/66/0	-	-
FTY	E6	Final Test Yield	-	-	3/3/0	3/3/0	-	-

QBS: Qual By Similarity, also known as Generic Data

Qual Device LMP7704MT/NOPB is qualified at MSL1 260C

Qual Device LMH0346MH/NOPB is qualified at MSL3 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2401-019

Qualification Report (CDAT)

Approve Date 27-August-2024

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74AXC4T245PWR	Qual Device: SN74HCS08PWR	Qual Device: TMUX1308PWR	Qual Device: MAX202IPWR	QBS Reference: TMUX1308QPWRQ1	QBS Reference: LMP8601EDRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	1/77/0*	3/231/0*
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0		-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	3/231/0		-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	3/231/0		-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	-	-	3/66/0		-
MQ		Assembly MQ	Per site specification	-	1/Pass	1/Pass	1/Pass	3/Pass	3/Pass	-

QBS: Qual By Similarity, also known as Generic Data

Qual Device SN74AXC4T245PWR is qualified at MSL1 260C

Qual Device SN74HCS08PWR is qualified at MSL1 260C

Qual Device TMUX1308PWR is qualified at MSL1 260C

Qual Device MAX202IPWR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and - 65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2402-077

Qualification Report (CDAT)

Approve Date 13-November-2023

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TPS35JE35JADDSER	QBS Process/Product Reference: TPS35AA38AGADDFRQ1	QBS Process Reference: PCM6260QRTVRQ1	QBS Package Reference: TPS37A010122DSKRQ1	QBS Package Reference: TMP117AIDRVR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	1/77/0	3/231/0	1/77/0	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	1/77/0	3/231/0	3/231/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	1/77/0	-	-	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	1/77/0	3/135/0	3/135/0	3/231/0
HTOL	B1	Life Test	125C	1000 Hours	-	1/77/0	3/231/0	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	-	3/231/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/2400/0	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	1/15/0	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	1/15/0	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	1/10/0	3/30/0	3/30/0	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-	-	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	-	-	1/3/0
LU	E4	Latch-Up	Per JESD78	-	1/3/0	1/6/0	1/6/0	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	3/90/0	3/90/0	-	3/90/0

QBS: Qual By Similarity

Qual Device TPS35JE35JADDSER is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-NPD-2310-038

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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